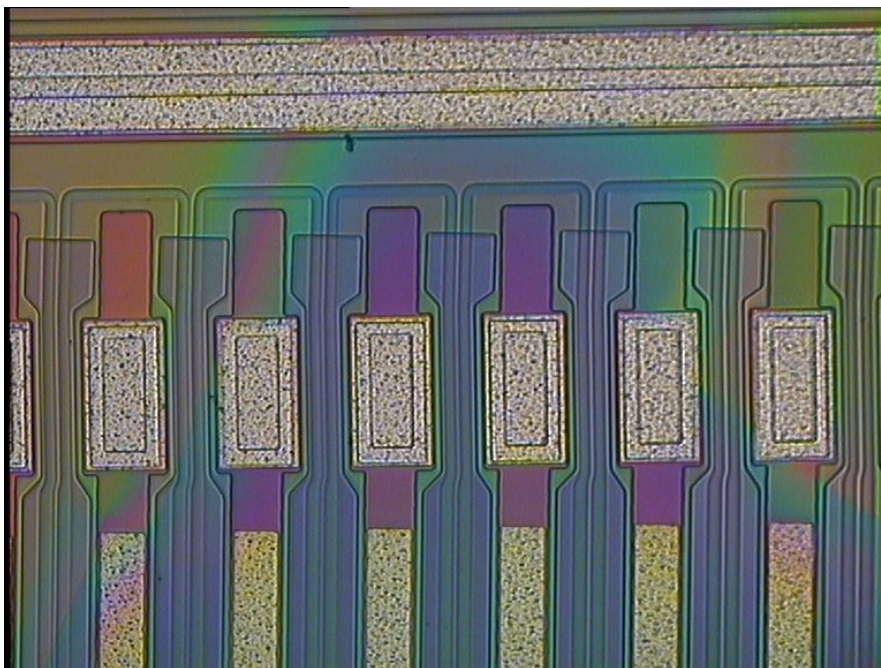
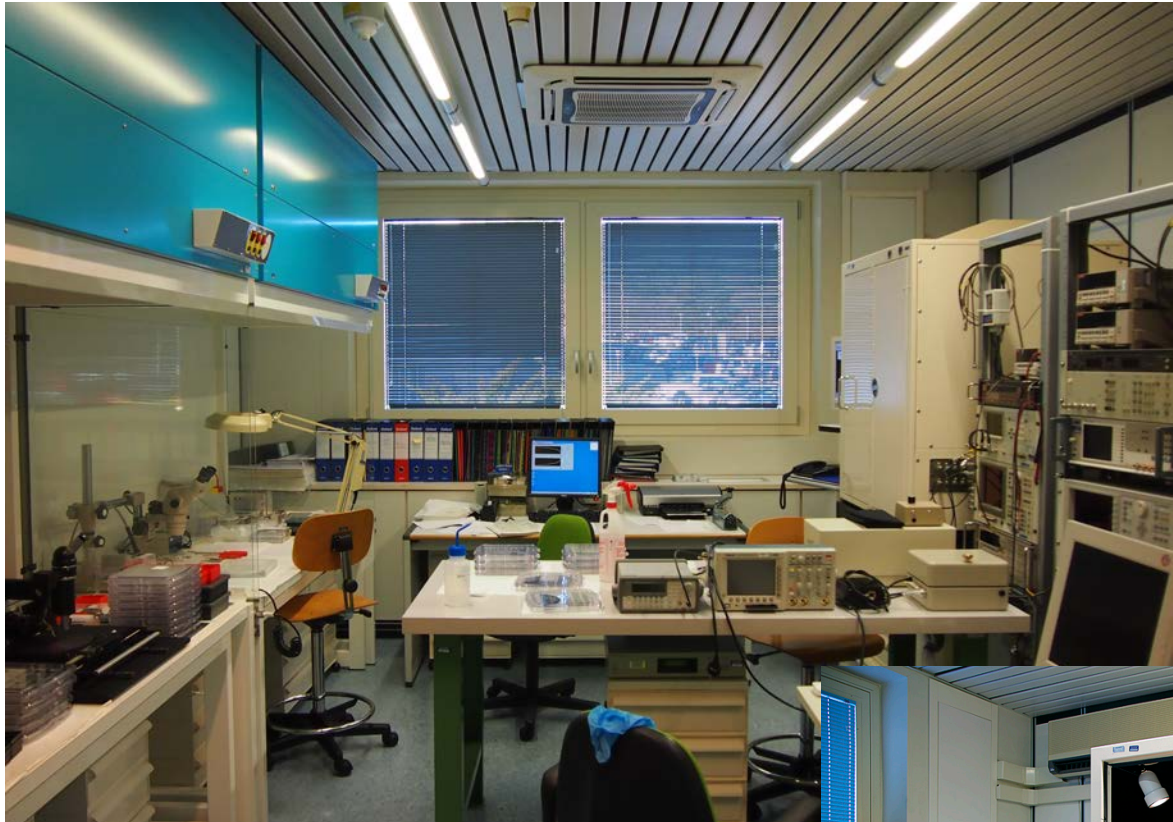


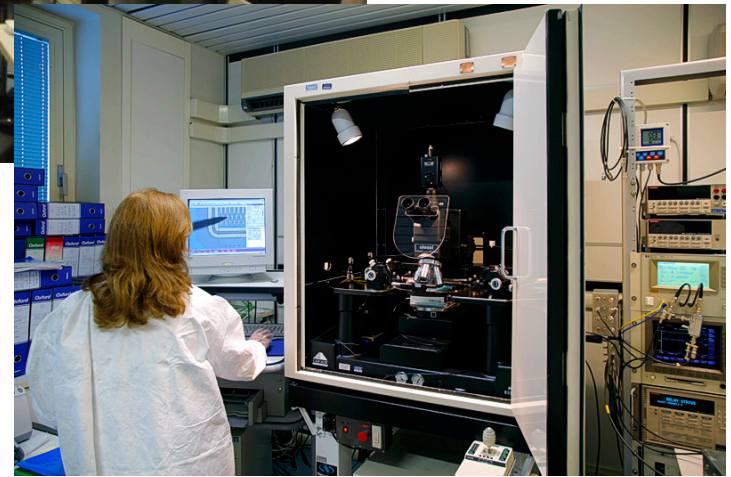
Electric characterisation and test of double sided Silicon Strip Detectors Silicon Drift Detectors Large area Linear Silicon Drift Detectors



Rashevskaya Irina
TIFPA
03 June 2020

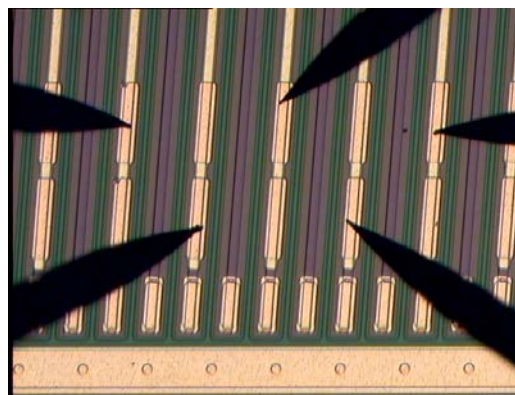
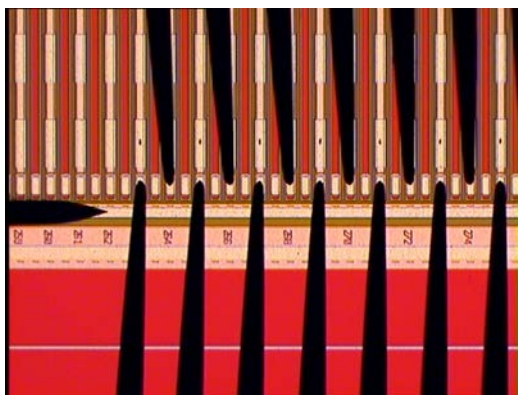


- Two semiautomatic probe station:
Alessi e Karlsus PA200
- Complete instrumentation for parametric measurements on semiconductor devices:
2 HP4141 HP4156A
HP4156C
2 HP4284A
KT237 KT6487 KT6517

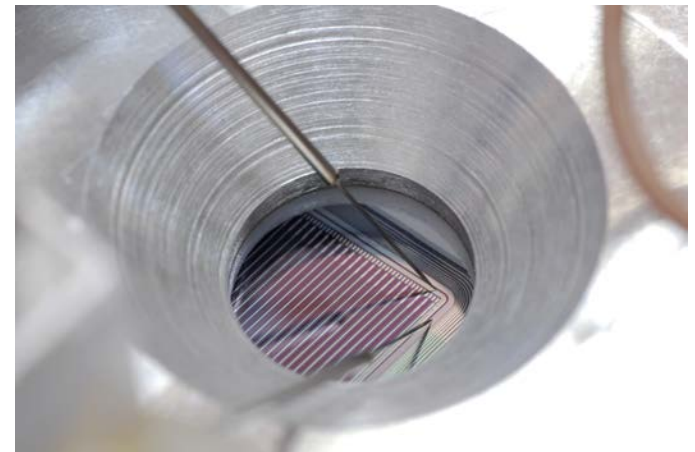
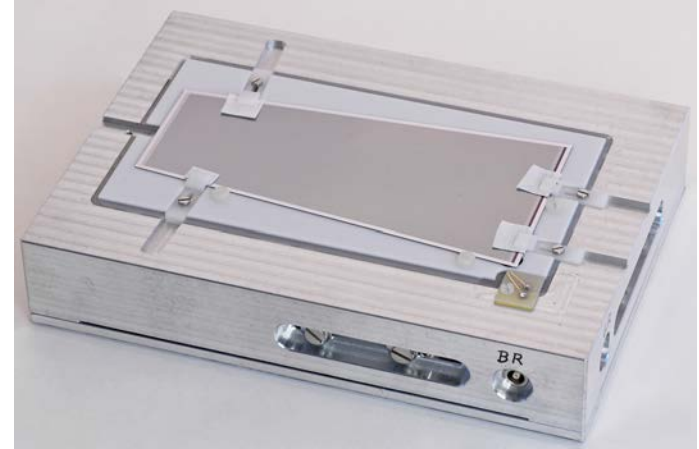
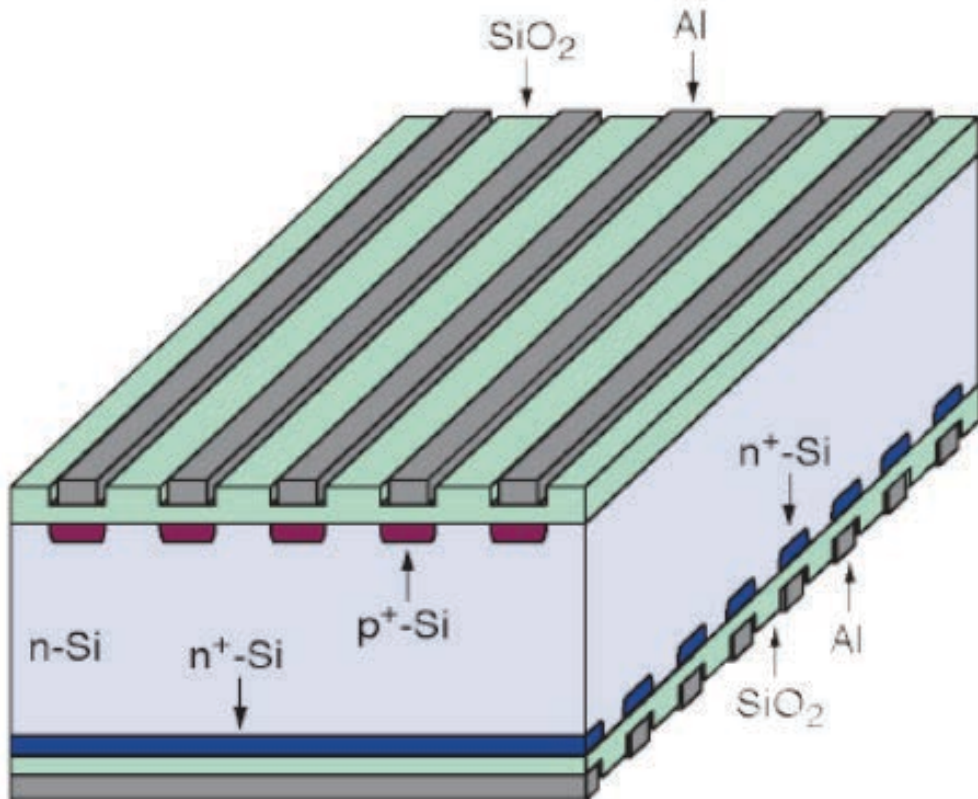


Characterization of double-sided silicon devices

- 400 Strip Detectors for Babar (SLAC)
- 3 batches of 20 wafers for IRST (now FBK)
- 2500 Strip Detectors for Alice (CERN)
- 80 Strip Detectors for LIMADOU (CSES)
- 100 Strip Detectors for Bell2 (Giappone)
- 5 batches (FBK) of DRIFT sensors 20 wafer for Redsox
- 2 batches (FBK) of 20 wafers of Linear DRIFT Detectors

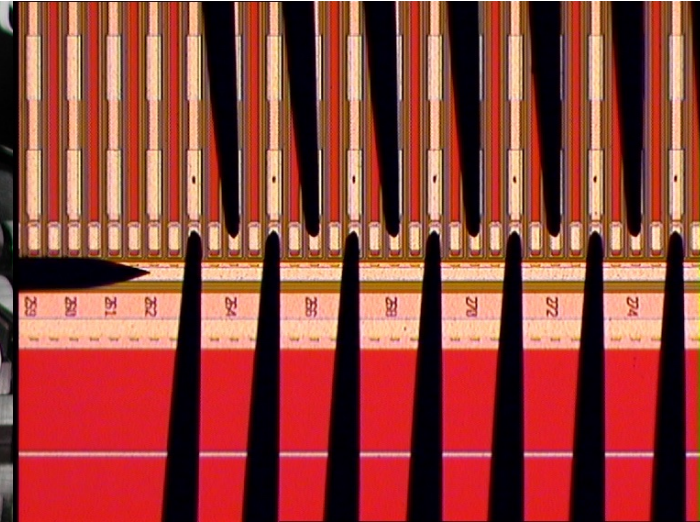
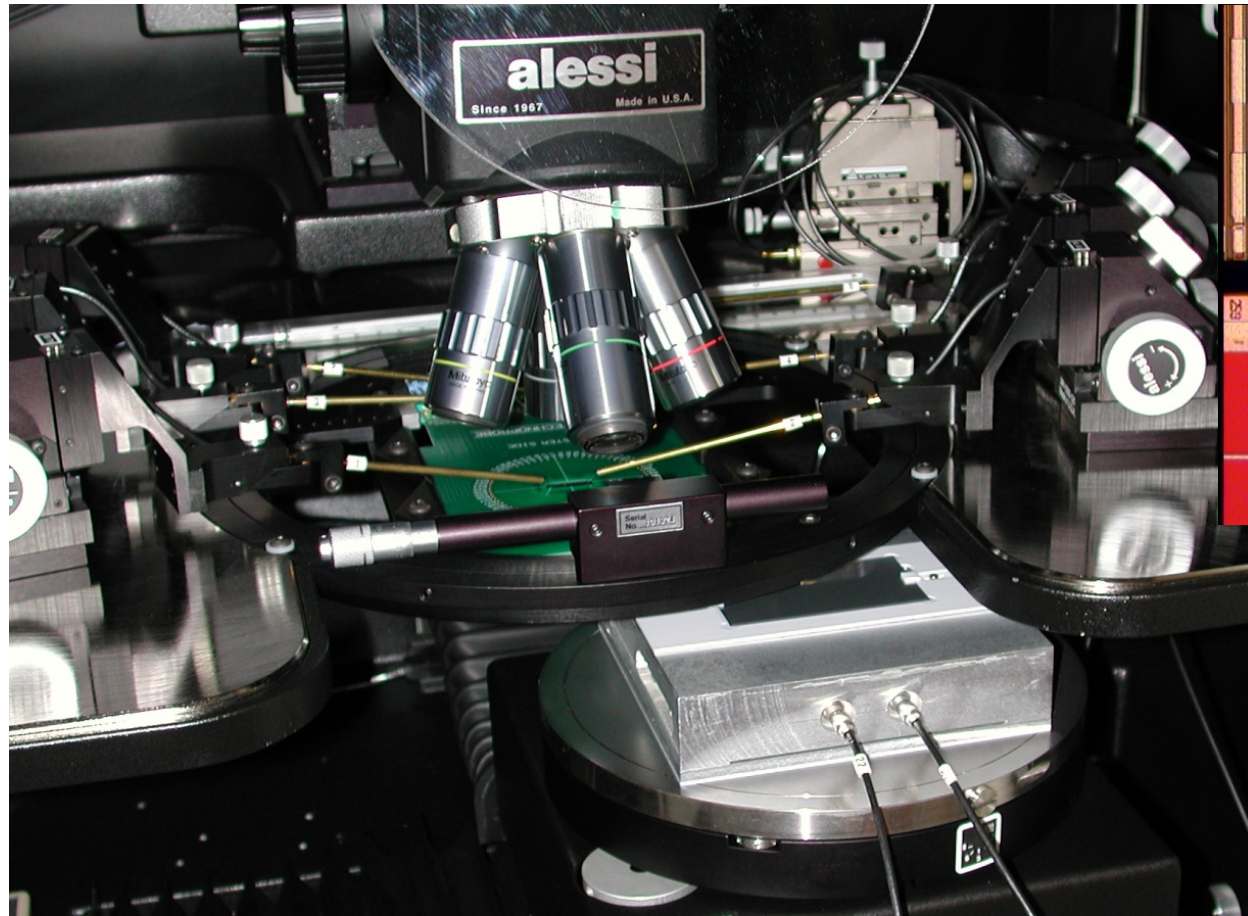


Silicon Strip Detector Bell2



Contact set-up for a trapezoidal sensors:

- one needle contact Bias Ring
- one needle contact Guard Ring



The detector support is
mounted on the probe
station chuck

- held by vacuum
- contacts to back-side
available through
coaxial connectors



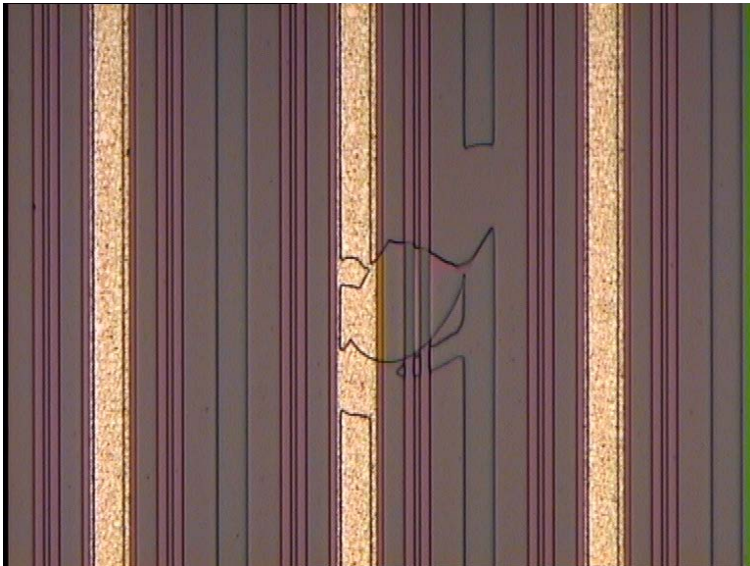
Standard Sensor Testing Procedure

The applied testing sequence is:

- Mount the sensor n -side-up on the jig
- I - V measurement for the whole sensor and one n -side strip
- AC (metal) strip Scan on n -side (along the long edge), using the 160 μm probe card
- DC (implanted) STRIP SCAN on n -side, using the 160 μm probe card to contact the readout strips (the non-readout strips are not accessible: no contact pad is present)
- Mount the sensor p -side-up on the jig, after repositioning one of the clamps
- AC strip Scan on p -side (along the short edge), using the 100 μm probe card to contact (in two successive steps) all 50 μm pitch metal strips
- DC STRIP SCAN on p -side, using the 100 μm probe card to contact (in two steps) the 50 μm pitch implanted readout strips (the non-readout ones are not accessible)

The standard test allows detecting all types of defects affecting strips:

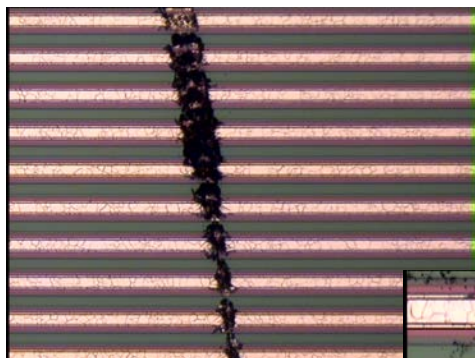
- DC strip with leakage current above spec (20nA)
- DC strip with insulation resistance below spec (50 M Ω)
- Broken AC capacitors
- Metal short between adjacent AC strips
- Interruption of the metal strip (metal open)



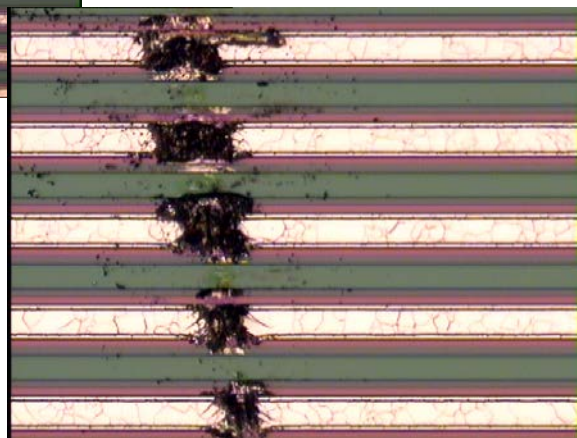
Defect 3 in 1

- open n strip
- open p-stop
- high current p – n contact

- The standard acceptance test includes:
 - immediate analysis of each measurement to identify defective strips
 - optical inspection of dubious cases
 - separation of shorts whenever possible



- From the AC scan:
 - No broken AC capacitors
 - Five shorted metal strips



- Shorts **separated** with a tungsten probe mounted on a manipulator
- Involved AC capacitors retested after separation. OK:
 - No broken AC capacitors
 - No shorts
 - No opens



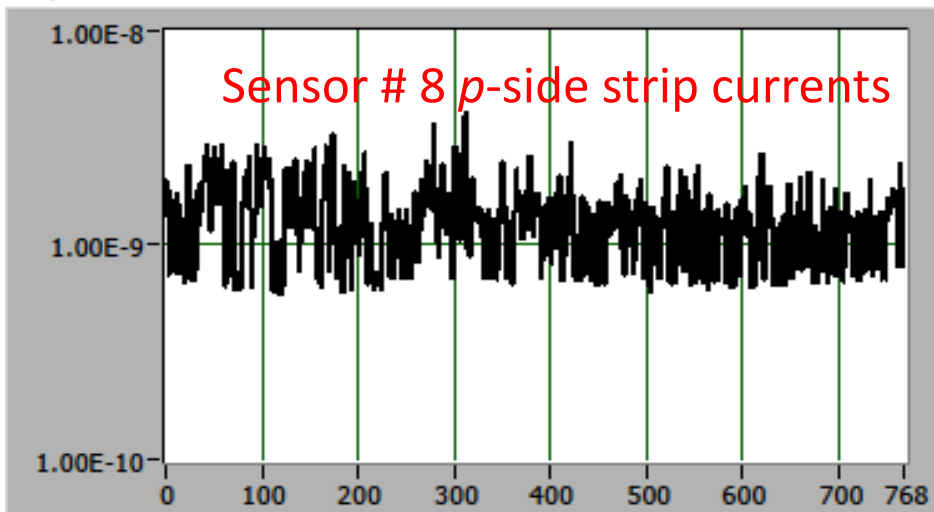
Test of Hamamatsu Sensors

- Many additional dedicated tests were made in order to better clarify some issues emerged from the standard test
- Some inconsistencies in Hamamatsu tests have been found (later acknowledged by HPK).
- A strip insulation problem on p -side has been found and extensively investigated.

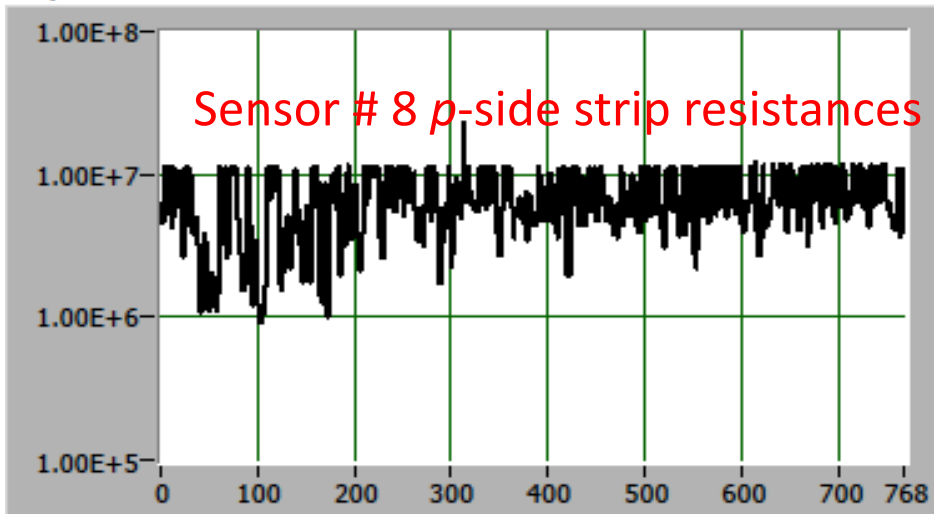
HPK Sensor # 8

p -side DC scan

Strip current



Strip resistance

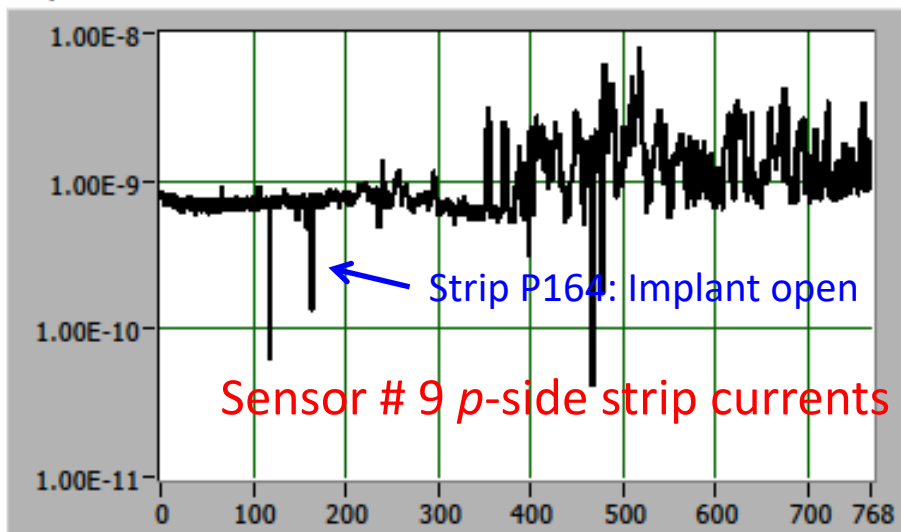


Many strips have lower than normal, varying resistance while many others have quite uniform R , slightly above $10\text{ M}\Omega$ (target value). This suggests the occurrence of local surface inversion spots between the strips.

The fluctuating currents ($< 1\text{ nA}$ variations) are due to small voltage offsets between the measuring channels, interconnected by a few $\text{M}\Omega$ resistance.

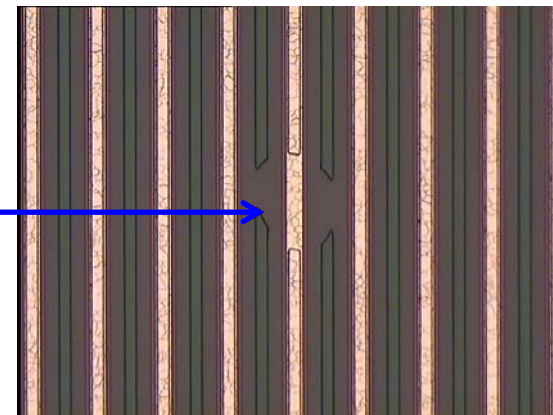
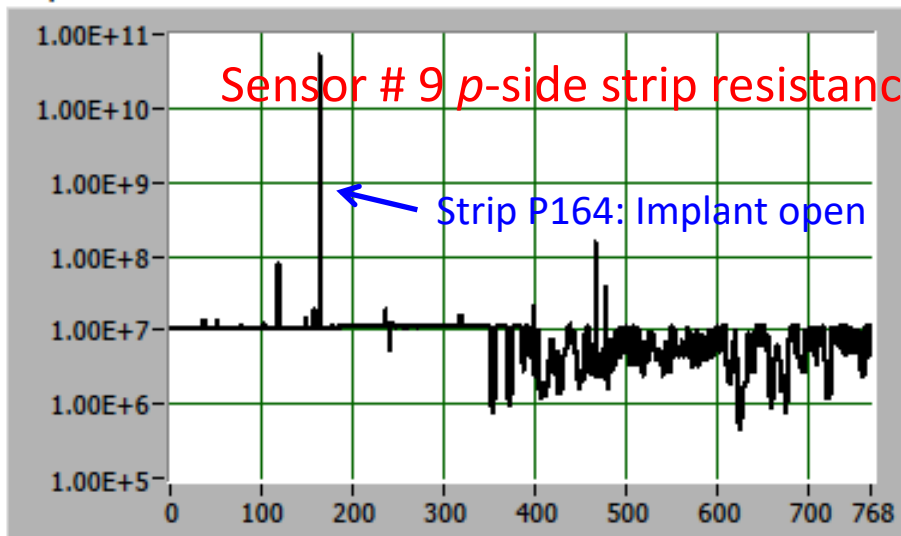
HPK Sensor # 9 p-side DC scan

Strip current



Similar problem as found on sensor # 8, but limited to the second half of the sensor.

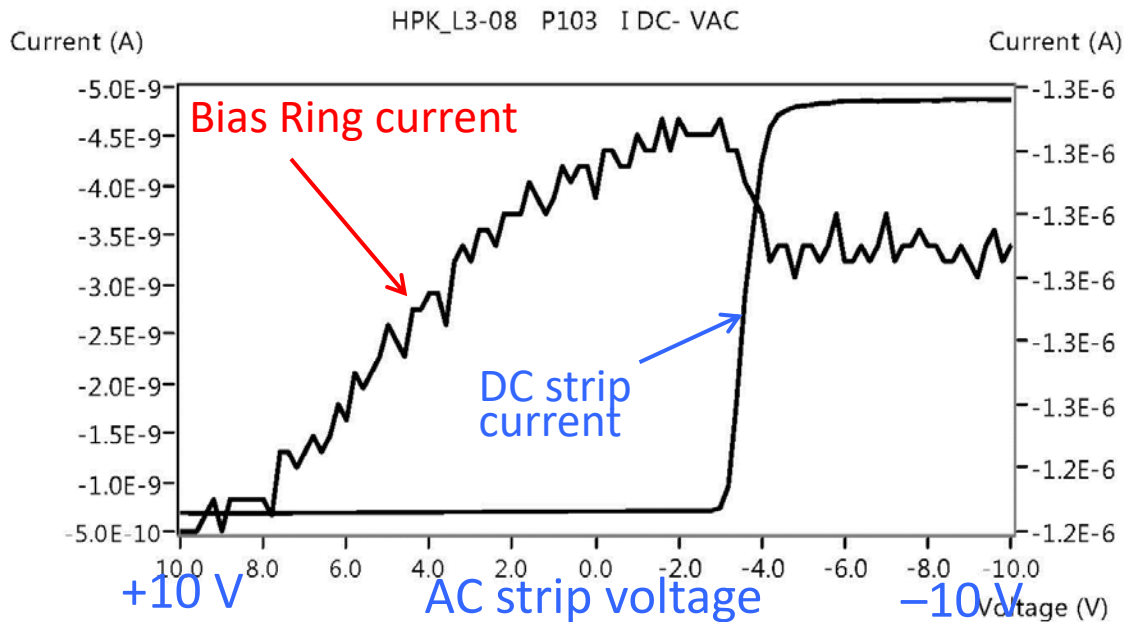
Strip resistance





Investigation on the Strip Insulation Issue

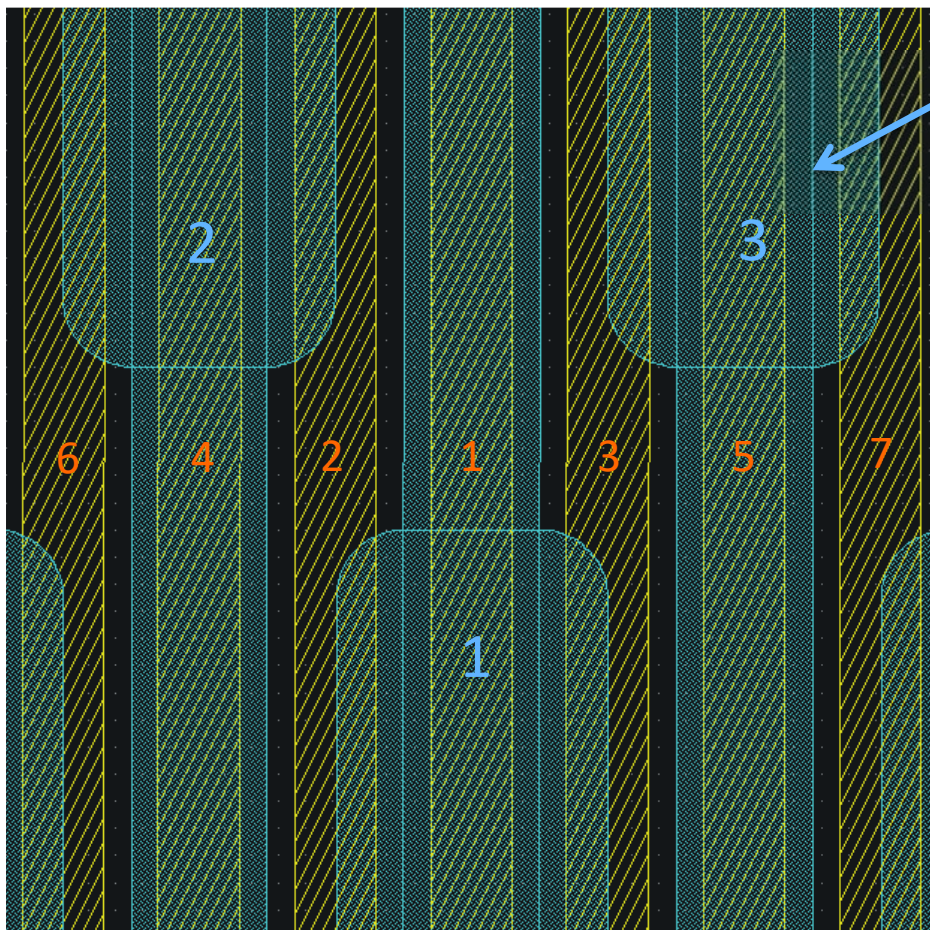
- Sensors showed signs of local surface inversion between the strips
- An attempt was made to control the interface condition by applying voltage to the insulated metal AC strips:
 - three contiguous AC strips contacted by manipulators
 - the central DC strip current has been measured as a function of the voltage applied to the three AC strips



- $V_{bias} = 150 \text{ V}$
- V_{AC} of three strips (#102, 103, 104) swept from +10 V to -10 V
- V of DC strips $\approx V_{BR} = 0$

- For $V_{AC} > -3 \text{ V}$ we measure the leakage current of a single p^+ strip ($\approx 0.7 \text{ nA}$)
- For $V_{AC} < -4 \text{ V}$ the DC strip current becomes \approx **seven times higher**, indicating that it is collecting the current of seven contiguous strips
- A corresponding drop of current is observed on the Bias Ring
- The transition is rather sharp and reversible, with no appreciable hysteresis

Parasitic MOSFET on p-side

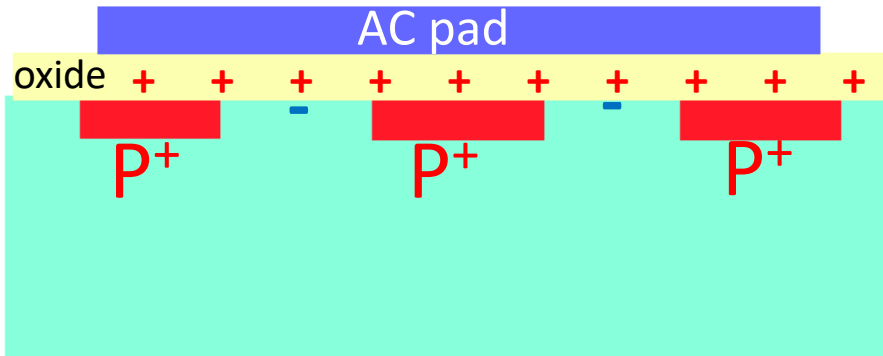


Note: The layout detail shown actually belongs to a wedge (Micron) sensor, but the situation is very similar for rectangular (HPK) sensors.

- The **AC pad** overlaps the two adjacent implanted strips, acting as the metal gate of a parasitic P-MOSFET.
- If a negative voltage $< V_{thr}$ is applied, say, to **three** contiguous **AC strips**, then **seven implanted strips** (3 readout and 4 non-readout) **get shorted together**.
- This effect is immediately reversible by changing the voltage applied to the AC pads.
- However, the parasitic MOSFET may also be switched on by *ions slowly drifting* on the outer sensor surface or in the dielectric layers. This may lead to *inversion of portions of the interface not directly controlled by the metal gate*, an effect that is subject to large and poorly controllable hysteresis.

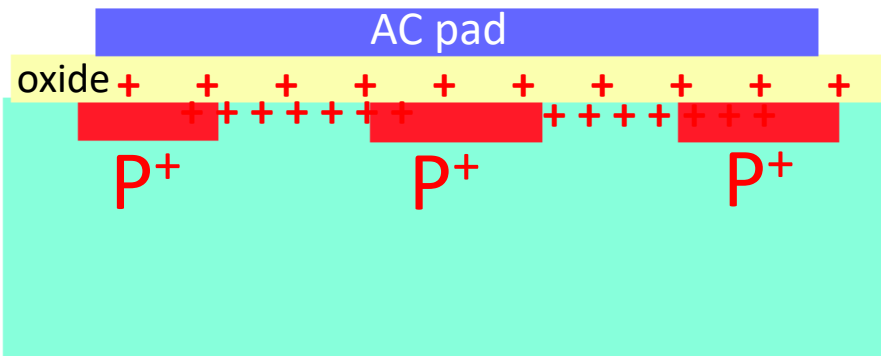
Parasitic MOSFET on p-side

$$V_{AC} = 0 \text{ V}$$



When $V_{AC} = 0$ (or a value $> V_{thr} \approx -3 \text{ V}$)
surface is accumulated/depleted
==> strips are **insulated**

$$V_{AC} = -3 \text{ V}$$

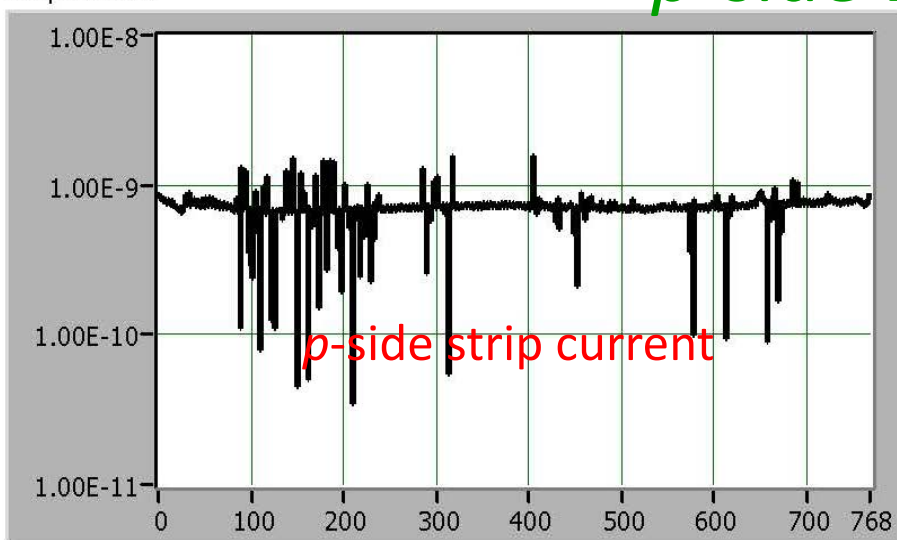


When $V_{AC} \leq V_{thr} \approx -3 \text{ V}$, surface is
inverted
==> strips are **shorted together**

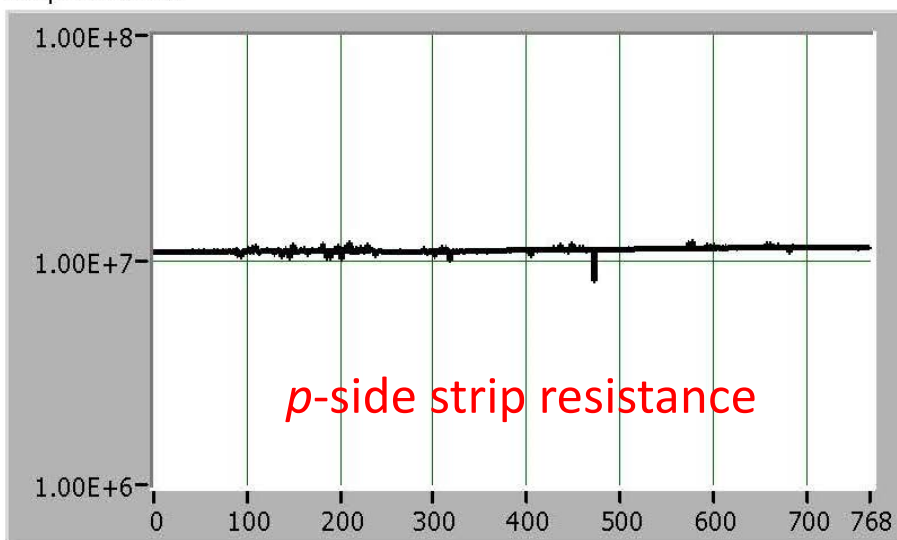
HPK Sensor # 8

p-side DC scan # 2

Strip current



Strip resistance



After AC scan with

$$V_{AC} = +10 V$$

0 strips have $R < 10 M\Omega$

(the one shown in the plot had a probe contact problem)



By biasing all AC strips at +10 V for a short time (10 s) strip insulation has been recovered

Summary of strip insulation on HPK sensors

It's easy to invert the surface because of two reasons:

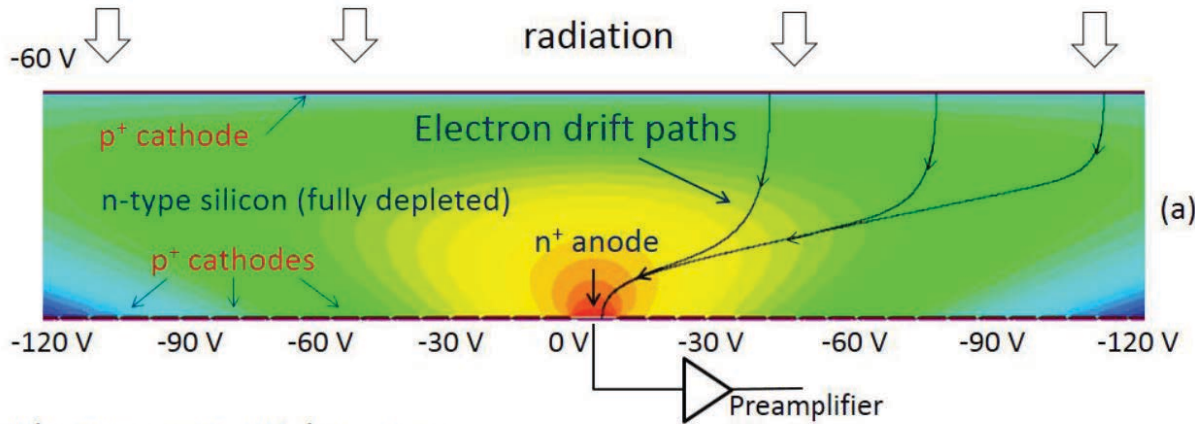
- Low oxide charge on (100) oriented substrates
- Small pitch of p strip and AC pad that completely cover the gap between adjacent strips

The problem could likely come up during the following manipulations of the sensor, in particular during the complex assembly phase (contact with teflon-covered jigs, kapton...).

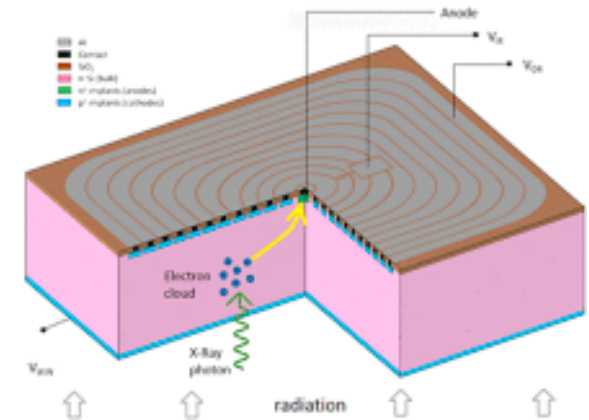
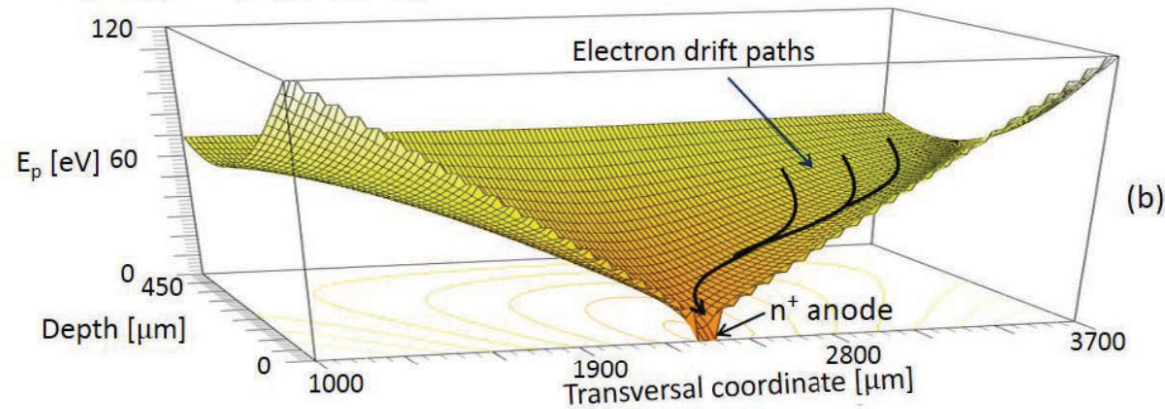
A final recommendation

Because of the danger of surface inversion, the voltage applied to the readout chips (relative to the Bias Ring) should never become more negative than about -2.5 V (taking into account the fact that the APV25 input is at +0.75 V relative to the local reference).

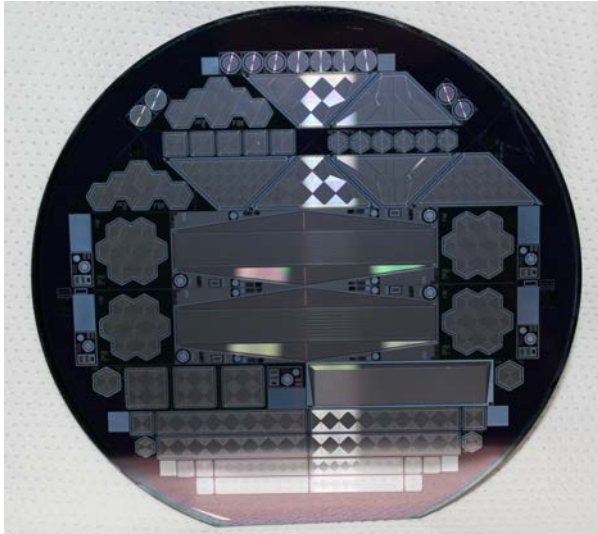
Silicon Drift Detector



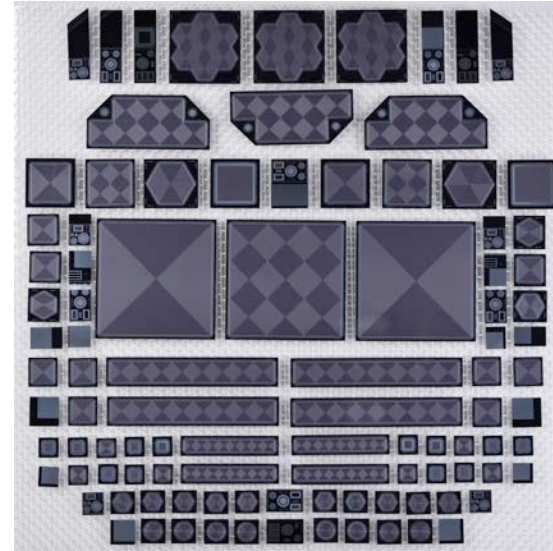
Electron potential energy



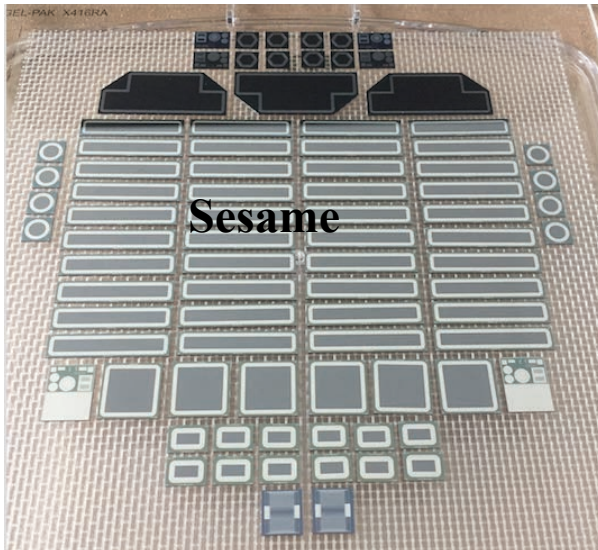
Silicon Drift Detector - FBK



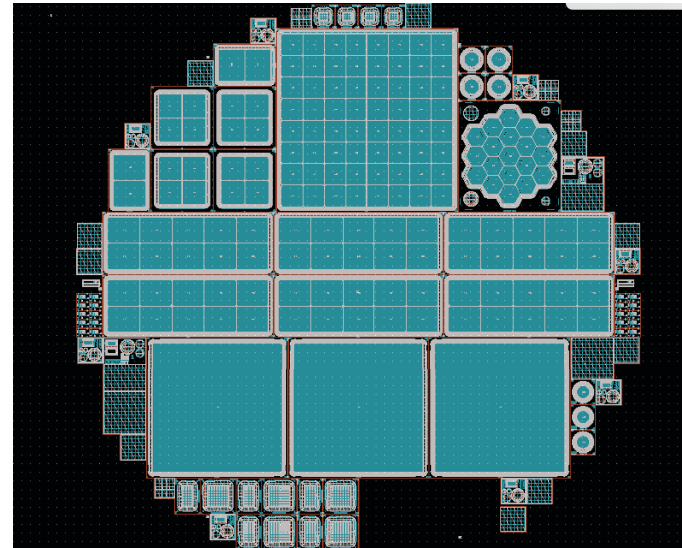
**RedSox2
2015**



**Redsox3
2016**

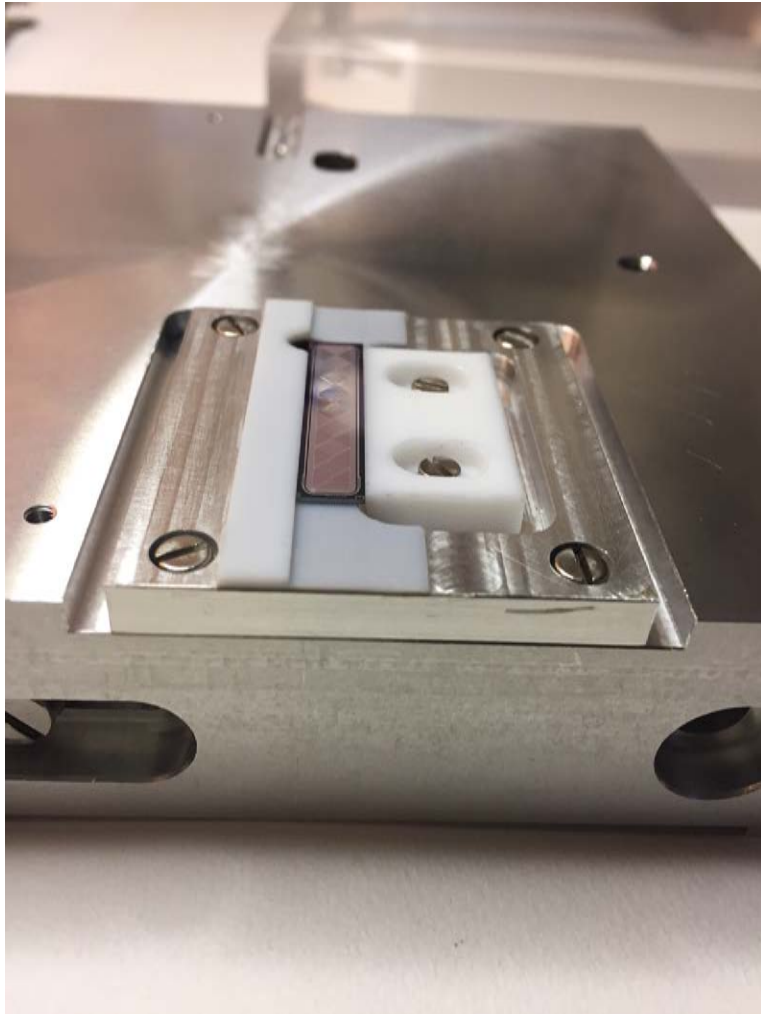


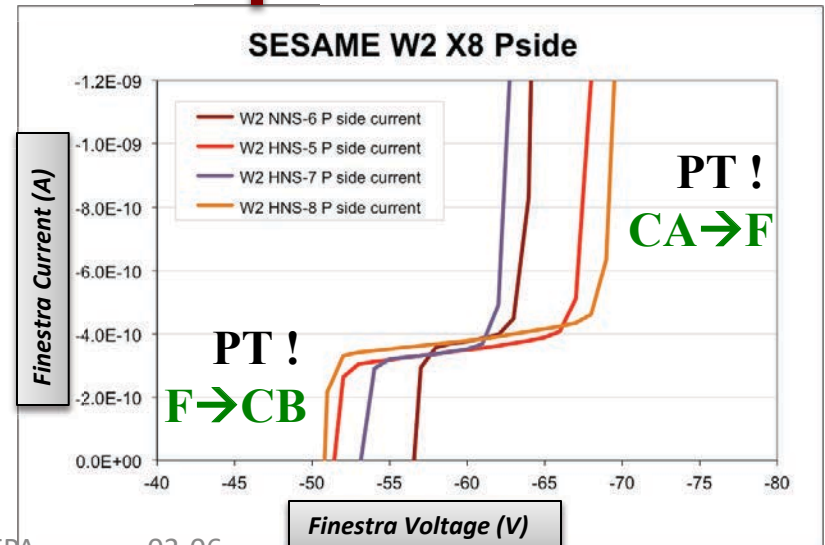
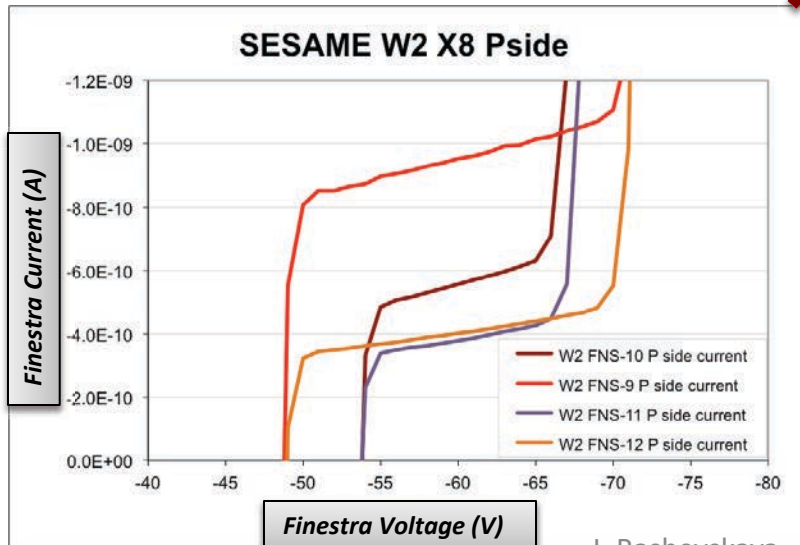
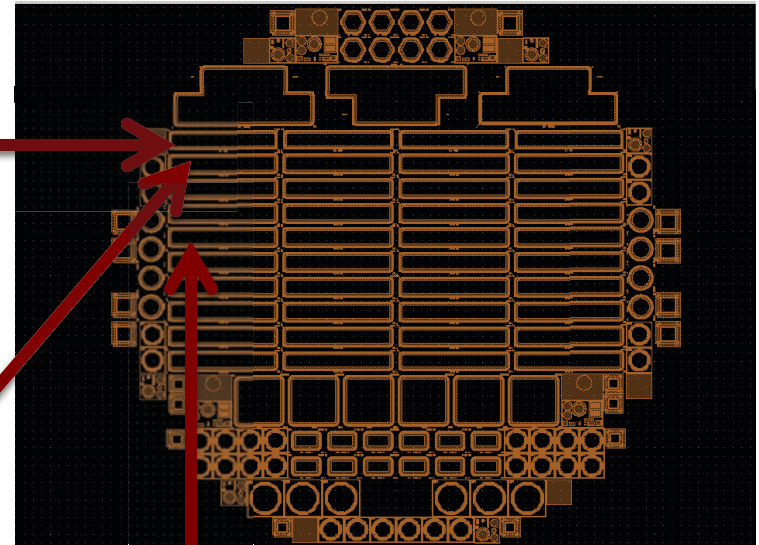
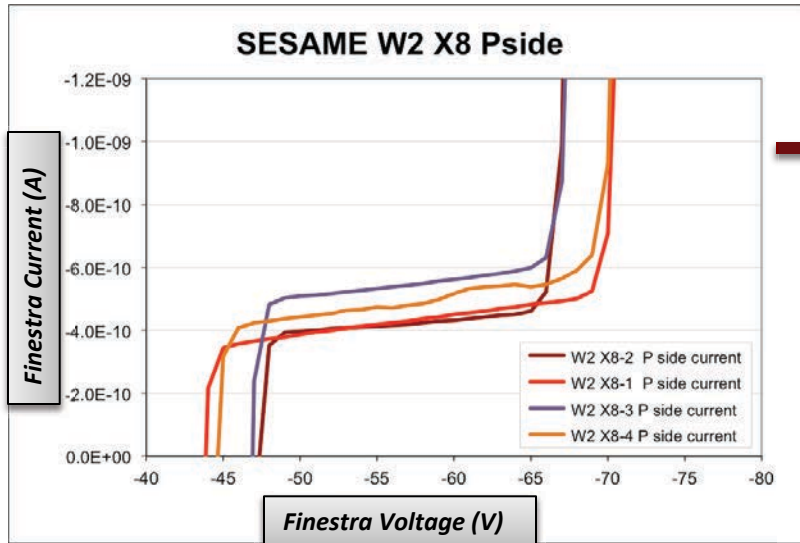
**Sesame
2018**



**Redsox4
2019**

Sesame Sensors



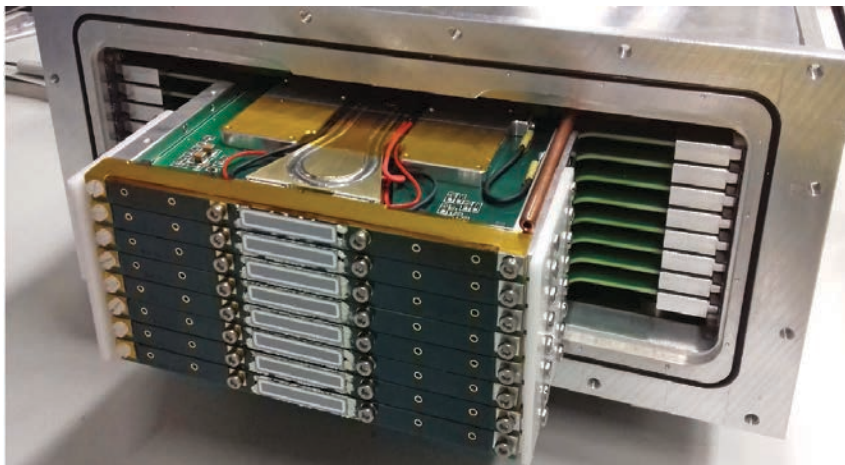
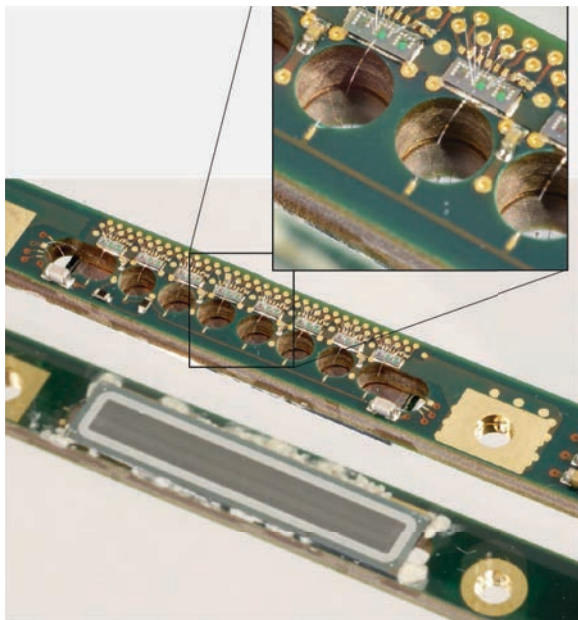


Lotto Sesame 8 cells 9mm2									TEST				
		I-V V	I-V GR CB, CB, N+	Anodo	I Anodo A	R Ohm	IP+ pA	Comments	Tested 8	Excell 2	Good 4	Total 6	Yield 75%
T=26 C									20pA 100pA				
W4 NNS-9		58V	983 207	1 2 3 4 5 6 7 8	1.17E-11 1.03E-11 7.05E-12 2.26E-11 7.00E-12 6.65E-12 6.75E-12 6.80E-12	1.22E+07 1.08E+07 1.30E+07 1.28E+07 1.24E+07 1.19E+07 1.15E+07 1.11E+07	-1.31E-09 -1.31E-09 -1.31E-09 -1.31E-09 -1.31E-09 -1.31E-09 -1.31E-09 -1.31E-09		1	1			
21/01/19	V_CA = -20V V_CB = -120V V_P = -60V	150V	666 1432										
Scheda 21													
T=25°C													
W4 NNS-10		57V	1068 298	1 2 3 4 5 6 7 8	6.65E-12 3.70E-11 6.60E-12 6.70E-12 6.60E-12 6.60E-12 6.55E-12 5.54E-11	1.05E+07 1.03E+07 1.01E+07 9.95E+06 9.85E+06 9.77E+06 9.70E+06 9.66E+06	-6.47E-10 -6.47E-10 -6.47E-10 -6.47E-10 -6.47E-10 -6.47E-10 -6.47E-10 -6.47E-10						
21/01/19	V_CA = -20V V_CB = -120V V_P = -60V	150V	1104 976										
Scheda 21													
T=25°C													
W4 NNS-11		55V	1038 274	1 2 3 4 5 6 7 8									
28/12/18	V_CA = -20V V_CB = -120V V_P = -60V	150V	1024 1076										
Misure P ^T													
T=25°C													
W4 NNS-12		56V	1020 255	1 2 3 4 5 6 7 8	7.25E-12 7.10E-12 7.00E-12 7.00E-12 3.36E-11 9.75E-12 1.83E-11 2.59E-11	1.25E+07 1.27E+07 1.26E+07 1.18E+07 1.10E+07 1.08E+07 1.08E+07 1.10E+07	-1.47E-09 -1.47E-09 -1.47E-09 -1.47E-09 -1.47E-09 -1.46E-09 -1.46E-09 -1.46E-09						
28/12/18	V_CA = -20V V_CB = -120V V_P = -60V	150V	602 1691										
Scheda 19													
T=25°C													
W4 NNS-5		57V	986 163	1 2 3 4 5 6 7 8	8.50E-12 8.20E-12 7.85E-12 7.25E-12 7.30E-12 7.25E-12 1.92E-11 7.55E-12	1.10E+07 1.21E+07 1.30E+07 1.29E+07 1.24E+07 1.18E+07 1.13E+07 1.09E+07	-6.45E-10 -6.44E-10 -6.44E-10 -6.44E-10 -6.44E-10 -6.44E-10 -6.44E-10 -6.44E-10						
28/12/18	V_CA = -20V V_CB = -120V V_P = -60V	150V	1030 778										
Scheda 19													
T=25°C													

The yield is
75 – 86%

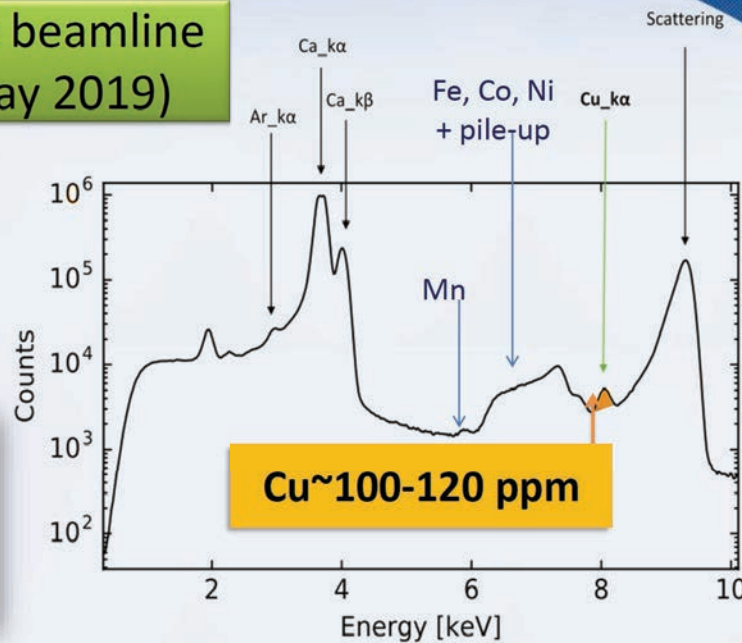
24 Excellent Sensors
were mounted
1 cel < 25pA

Typical cell
I anodes ~ 3pA
(35 pA/cm²)

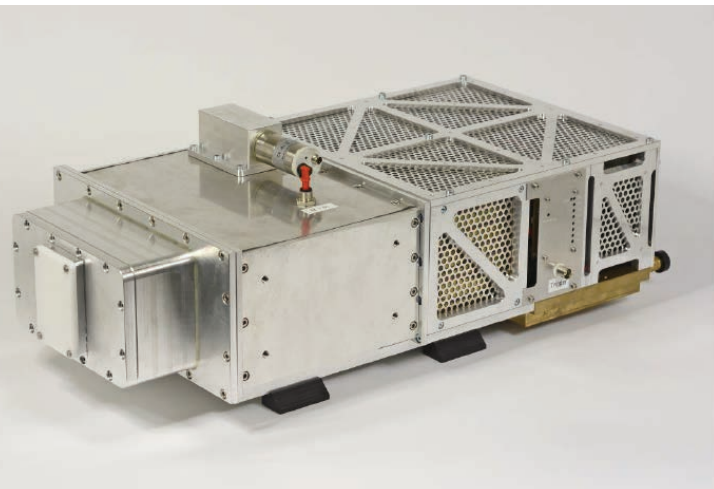


Heavy Metals Bio-monitoring

Elettra - XAFS beamline
MD-test (May 2019)



XAFS-SESAME Detector System

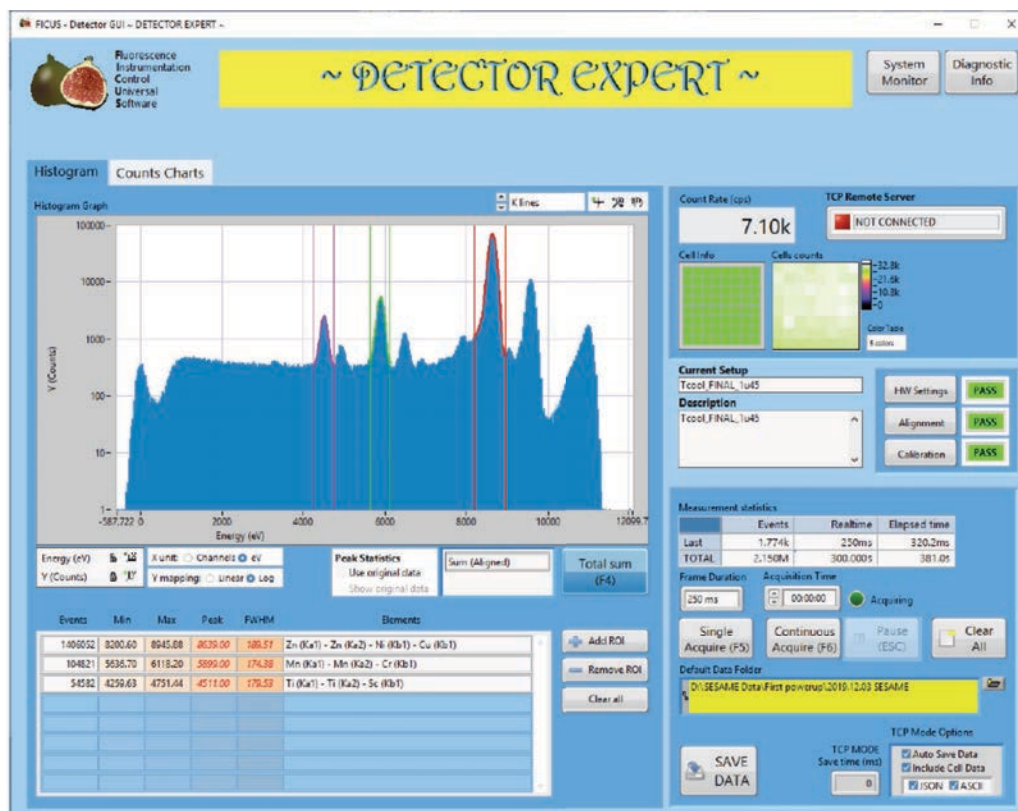


Tamb-1 μ 45 -5min –Mn $K\alpha$

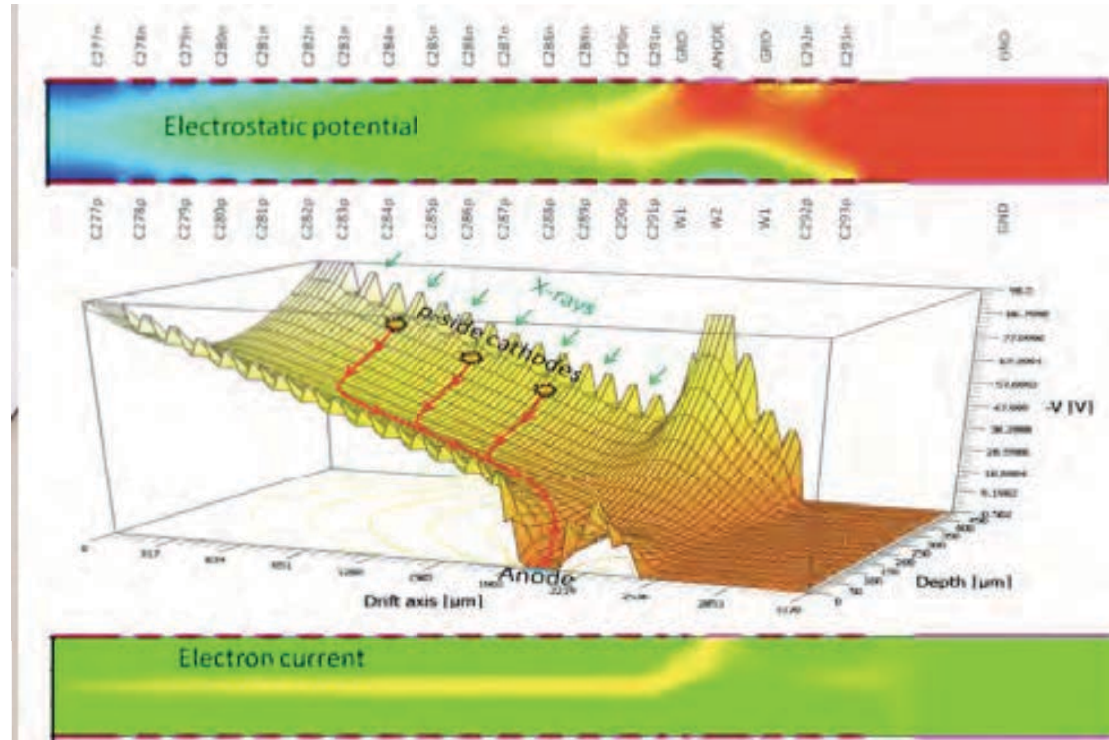
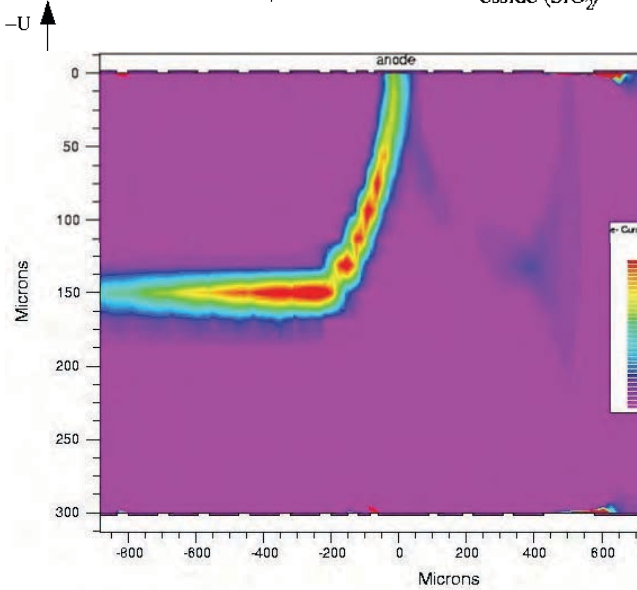
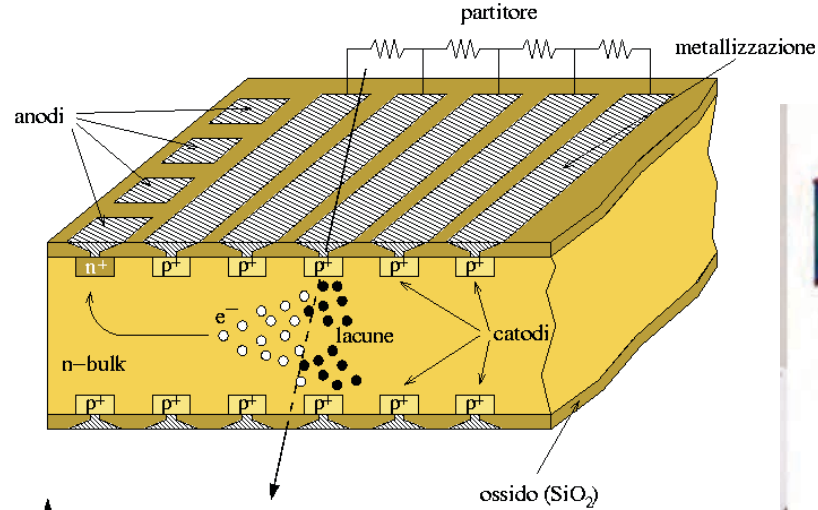
The resolution of the sum of the signal coming from all 64 channels is **168 eV**

Tcool-1 μ 45 -5min –Mn $K\alpha$

The resolution of the sum of the signal coming from all 64 channels is **162 eV**.

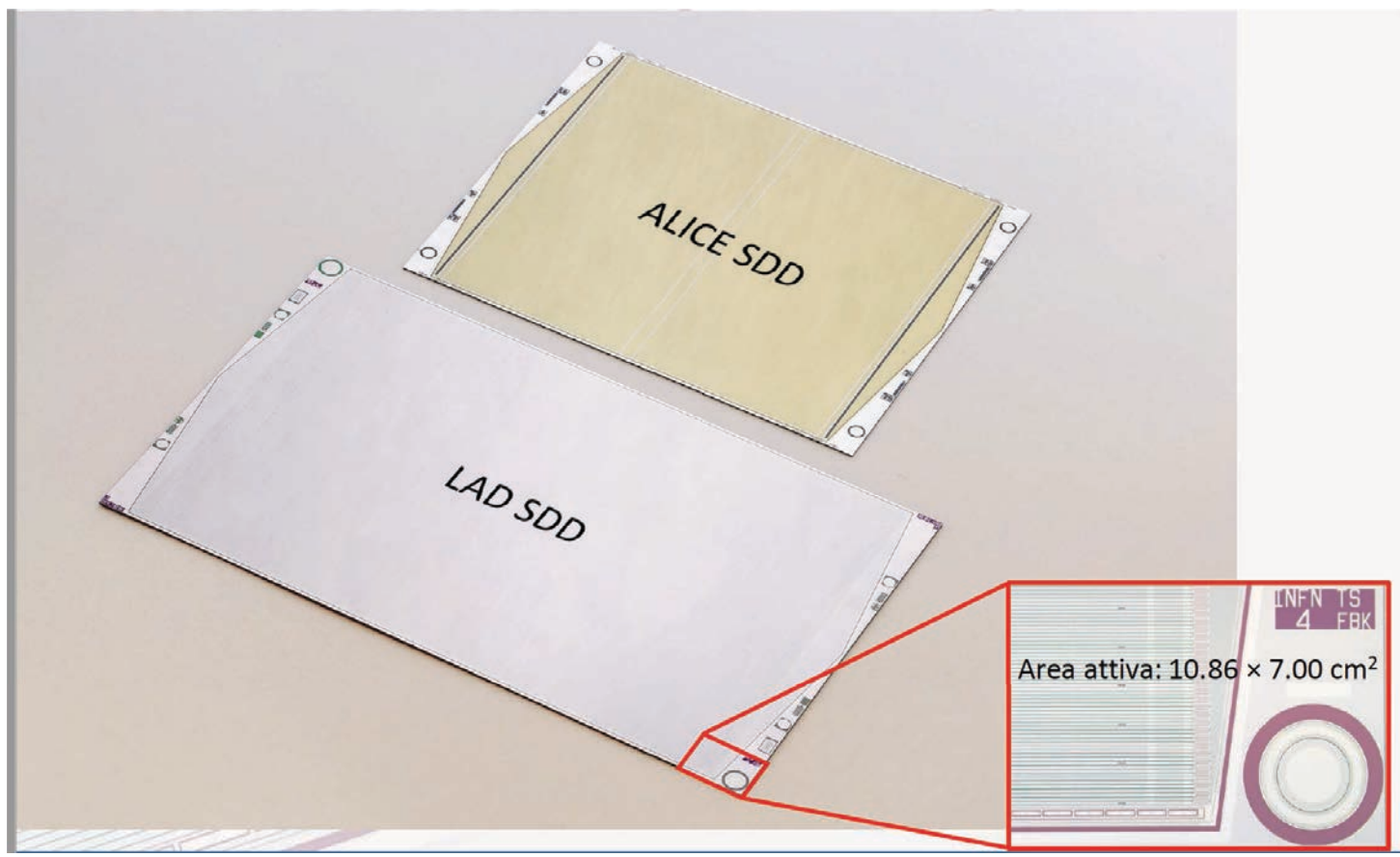


Linear Silicon Drift Detector

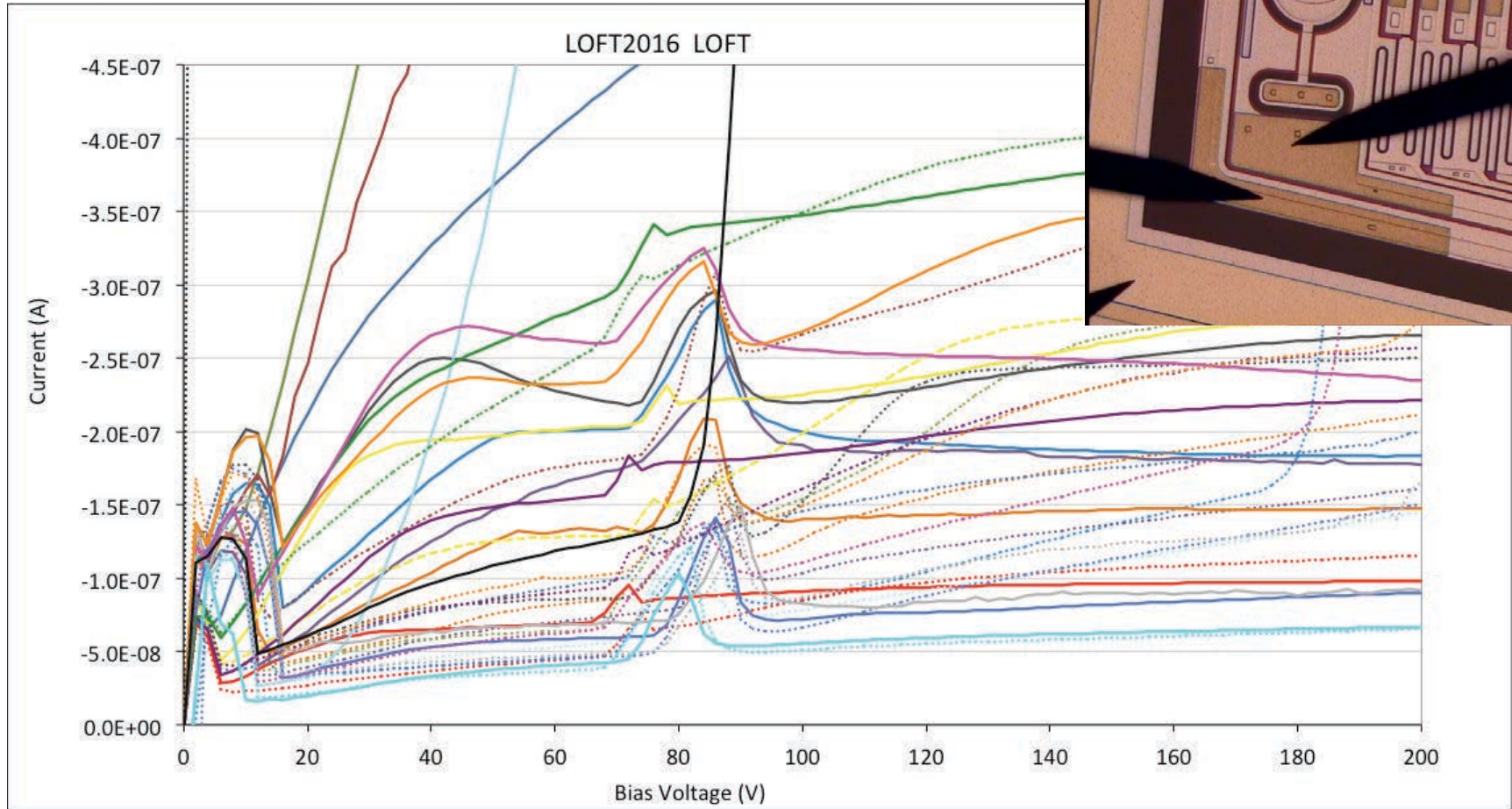


Linear Silicon Drift Detector

Large Area Silicon Drift Detectors for X-ray spectroscopy, timing and imaging designed by INFN Trieste and developed in collaboration with INAF (IAPS Rome, IASF Bo), Fondazione Bruno Kessler, PoliMi, University of Pavia, University of Bologna. More than 10 yrs R&D activity



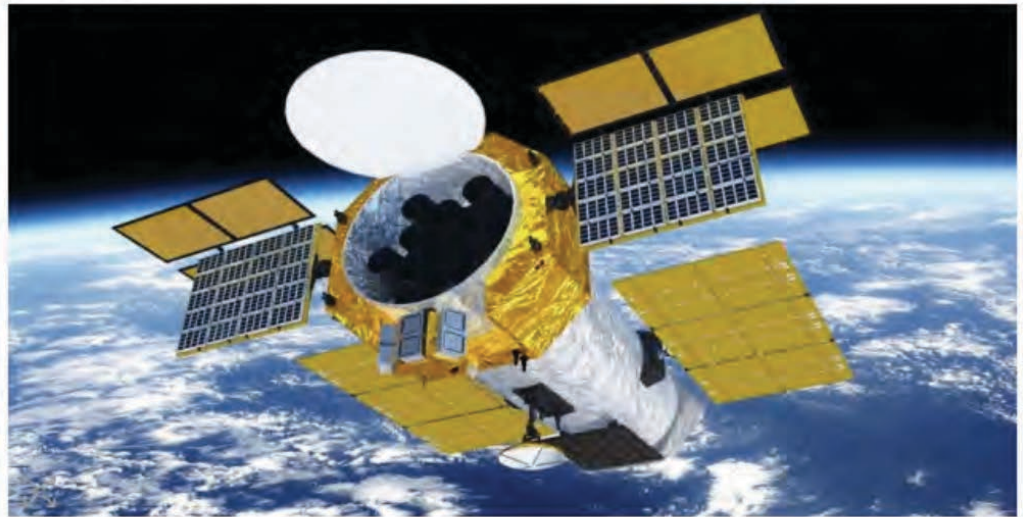
Linear Silicon Drift Detector



The enhanced X-ray Timing and Polarimetry mission (eXTP)

eXTP is conceived as a powerful and general observatory for compact Galactic and bright extragalactic objects to date. It will offer for the first time the most complete diagnostics of compact sources: excellent spectral, timing and polarimetry sensitivity on a single payload.

The eXTP Team is open to contributions from the wide scientific community. More info at:
<http://www.isdc.unige.ch/extp/>



The enhanced X-ray Timing and Polarimetry mission will cost around three billion yuan (£340m) and is set to launch by 2025 (courtesy: Institute of High Energy Physics)

the Large Area Detector (LAD):

a deployable set of **640** Silicon Drift Detectors, achieving a total effective area of $\sim 3.4 \text{ m}^2$ between 6 and 10 keV. The operational energy range is 2-30 keV and the achievable spectral resolution better than 250 eV. This is a non-imaging instrument, with the FoV limited to $<1^\circ$ FWHM by the usage of compact capillary plates.